SPECIFICATION

SPEC. No. C2011-1380
DATE : Sep. 26, 2011

SOSHARE

CUSTOMER'S PRODUCT NAME	TDK PRODUCT NAME MULTILAYER CERAMIC CHIP CAPACITORS C3225X5R1E226K

Please return this specification to TDK representatives.
If orders are placed without returned specification, please allow us to judge that specification is accepted by your side.

THIS SPECIFICATION IS RECEIVED

DATE: YEAR MONTH DAY

TDK-EPC Corporation
1-13-1, Nihonbashi, Chuo-ku, Tokyo
103-0027, Japan

ENGINEERING

ISSUED	CHECKED	APPROVED
N. Yanagibashi	T. Umuma	Hiroshi Saito
DATE Sep. 26. 2011	DATE Sep. 28. 2011	DATE Sep. 28. 2011

Sales Office _____

Sales Tel. _____ ( ) _____

PRODUCT CLASSIFICATION CODE	040320

1. SCOPE

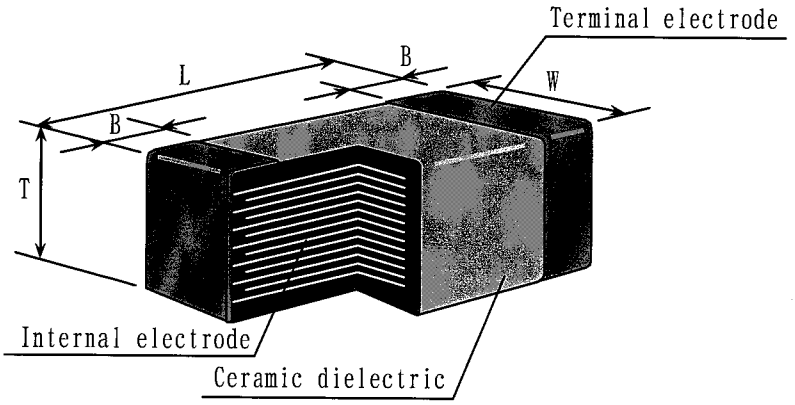
This specification is applicable to chip type multilayer ceramic capacitors with a priority over the other relevant specifications.
Production places defined in this specification shall be TDK-EPC Corporation,

EXPLANATORY NOTE:
This specification warrants the quality of the ceramic chip capacitor. The chips should be evaluated or confirmed a state of mounted on your product.
If the use of the chips go beyond the bounds of the specification, we can not afford to guarantee.

2. CODE CONSTRUCTION

C3225	X5R	1 E	226	K	T
(1)	(2)	(3)	(4)	(5)	(6)

(1) Type



Type	Dimensions (Unit : mm)			
TDK (EIA style)	L	W	T	B
C3225 (CC1210)	3.20±0.40	2.50±0.30	2.50±0.30	0.20 min.

(2) Temperature Characteristics (Details are shown in para. 9 No. 6)

(3) Rated Voltage

Symbol	Rated Voltage
1 E	DC 25 V

(4) Rated Capacitance

Stated in three digits and in units of pico farads (pF). The first and Second digits identify the first and second significant figures of the Capacitance, the third digit identifies the multiplier.

226 → 22,000,000pF

TDK

(5) Capacitance tolerance

Symbol	Tolerance
K	± 10 %

(6) Packaging

Symbol	Packaging
B	Bulk
T	Taping

3. OPERATING TEMPERATURE RANGE

Min. operating Temperature	Max. operating Temperature	Reference Temperature
-55℃	85℃	25℃

4. STORING CONDITION AND TERM

5 to 40℃ at 20 to 70%RH
6 months Max.

5. P. C. BOARD

This specification not applicable to Aluminum or some other substrate for such application, please state so and inquire separate specification.

6. RECOMMENDATION

It is recommended to provide a slit (about 1mm) on the board under the components to improve washing Flux.
And please make sure to dry detergent up completely before.

7. SOLDERING CONDITION

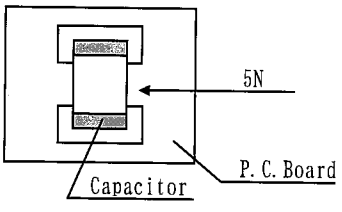
Reflow soldering only.

8. INDUSTRIAL WASTE DISPOSAL

Dispose this product as industrial waste in accordance with the industrial Waste Law.

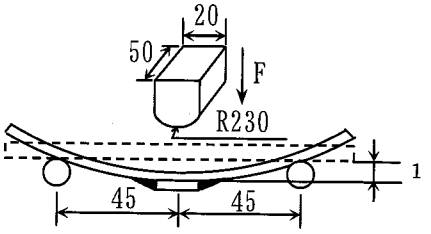
9. PERFORMANCE

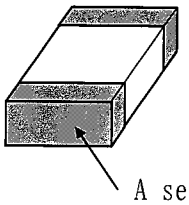
table 1

<table>
<tr><th>No.</th><th>Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td>1</td><td>External Appearance</td><td>No defects which may affect performance.</td><td>Inspect with magnifying glass (3×)</td></tr>
<tr><td>2</td><td>Insulation Resistance</td><td>4.5 MΩ min.</td><td>Apply rated voltage for 60s.</td></tr>
<tr><td>3</td><td>Voltage Proof</td><td>Withstand test voltage without insulation breakdown or other damage.</td><td>2.5 times of rated voltage
Above DC voltage shall be applied for 1～5s.
Charge / discharge current shall not exceed 50mA.</td></tr>
<tr><td>4</td><td>Capacitance</td><td>Within the specified tolerance.</td><td><table><tr><th>Measuring frequency</th><th>Measuring voltage</th></tr><tr><td>120Hz±20%</td><td>0.5±0.2V rms.</td></tr></table></td></tr>
<tr><td>5</td><td>Dissipation Factor</td><td>Characteristics<table><tr><th>T.C.</th><th>Rated Voltage</th><th>D.F.</th></tr><tr><td>X5R</td><td>25V DC</td><td>0.05 max.</td></tr></table></td><td><table><tr><th>Measuring frequency</th><th>Measuring voltage</th></tr><tr><td>120Hz±20%</td><td>0.5±0.2V rms.</td></tr></table></td></tr>
<tr><td>6</td><td>Temperature Characteristics of Capacitance</td><td><table><tr><th>Capacitance Change (%)</th></tr><tr><td>No voltage applied</td></tr><tr><td>X5R : ±15</td></tr></table></td><td>Capacitance shall be measured by the steps shown in the following table, after thermal equilibrium is obtained for each step.
ΔC be calculated ref. STEP3 reading.<table><tr><th>Step</th><th>Temperature (℃)</th></tr><tr><td>1</td><td>25 ± 2</td></tr><tr><td>2</td><td>-55 ± 2</td></tr><tr><td>3</td><td>25 ± 2</td></tr><tr><td>4</td><td>85 ± 2</td></tr></table></td></tr>
<tr><td>7</td><td>Robustness of Terminations</td><td>No sign of termination coming off, breakage of ceramic, or other abnormal signs.</td><td>Reflow solder the capacitor on a P.C. Board shown in Appendix2 and apply a pushing force of 5N for 10±1s.
 
</td></tr>
</table>

TDK

(continued)

<table>
<tr><th>No.</th><th colspan="2">Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td>8</td><td colspan="2">Bending</td><td>No mechanical damage.</td><td>Reflow solder the capacitor on a P.C.Board shown in Appendix1 and Bend it for 1mm.
 

(Unit : mm)</td></tr>
<tr><td>9</td><td colspan="2">Solderability</td><td>New solder to cover over 75% of termination.
25% may have pin holes or rough spots but not concentrated in one spot.
Ceramic surface of A sections shall not be exposed due to melting or shifting of termination material.
 
</td><td>Completely soak both terminations in solder at 235±5℃ for 2±0.5s.
Solder : H63A(JIS Z 3282)
Flux : Isopropyl alcohol(JIS K 8839)
Rosin(JIS K 5902)
25% solid solution.</td></tr>
<tr><td rowspan="5">10</td><td rowspan="5">Resistance to solder heat</td><td>External appearance</td><td>No cracks are allowed and terminations shall be covered at least 60% with new solder.</td><td rowspan="5">Completely soak both terminations in solder at 260±5℃ for 5±1s.
Preheating condition
Temp. : 150±10℃
Time : 1～2min.
Flux : Isopropyl alcohol(JIS K 8839)
Rosin(JIS K 5902)
25% solid solution.
Solder : H63A(JIS Z 3282)
Leave the capacitors in ambient condition for 48±4h before measurement.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X5R</td><td>±7.5 %</td></tr></table></td></tr>
<tr><td>D.F.</td><td>Meet the initial spec.</td></tr>
<tr><td>Insulation Resistance</td><td>Meet the initial spec.</td></tr>
<tr><td>Voltage proof</td><td>No insulation breakdown or other damage.</td></tr>
<tr><td rowspan="4">11</td><td rowspan="4">Vibration</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Reflow Solder the capacitors on a P.C.Board shown in Appendix2 before testing.
Vibrate the capacitor with amplitude of 1.5mm P-P changing the frequencies from 10Hz to 55Hz and back to 10Hz in about 1min.
Repeat this for 2h each in 3 perpendicular directions.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X5R</td><td>±7.5 %</td></tr></table></td></tr>
<tr><td>D.F.</td><td>Meet the initial spec.</td></tr>
</table>

TDK

(continued)

<table>
<tr><th>No.</th><th colspan="2">Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td>12</td><td>Temperature cycle</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="5">Reflow Solder the capacitors on a P. C. Board shown in Appendix2 before testing.

Expose the capacitors in the condition step1 through 4 and repeat 5 times consecutively.

Leave the capacitors in ambient condition for 48±4h before measurement.

Step | Temperature (℃) | Time (min.)
1 | -55 ± 3 | 30±3
2 | Reference Temp. | 2～5
3 | 85 ± 2 | 30±2
4 | Reference Temp. | 2～5</td></tr>
<tr><td></td><td></td><td>Capacitance</td><td>Characteristics | Change from the value before test
X5R | ± 12.5 %</td></tr>
<tr><td></td><td></td><td>D. F.</td><td>Meet the initial spec.</td></tr>
<tr><td></td><td></td><td>Insulation Resistance</td><td>Meet the initial spec.</td></tr>
<tr><td></td><td></td><td>Voltage proof</td><td>No insulation breakdown or other damage.</td></tr>
<tr><td>13</td><td>Moisture Resistance (Steady State)</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Reflow Solder the capacitors on a P. C. Board shown in Appendix2 before testing.

Leave at temperature 40±2℃, 90 to 95%RH for 500 +24, 0h.

Leave the capacitors in ambient condition for 48±4h before measurement.</td></tr>
<tr><td></td><td></td><td>Capacitance</td><td>Characteristics | Change from the value before test
X5R | ± 25 %</td></tr>
<tr><td></td><td></td><td>D. F.</td><td>characteristics
X5R : 200% of initial spec max.</td></tr>
<tr><td></td><td></td><td>Insulation Resistance</td><td>0.4 MΩ min.</td></tr>
<tr><td>14</td><td>Moisture Resistance</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Reflow Solder the capacitors on a P. C. Board shown in Appendix2 before testing.

Apply the rated voltage at temperature 40±2℃ and 90 to 95%RH for 500 +24, 0h.

Charge/discharge current shall not exceed 50mA.

Leave the capacitors in ambient condition for 48±4h before measurement.

Voltage conditioning
Voltage treat the capacitor under testing temperature and voltage for 1hour.
Leave the capacitors in ambient condition for48±4h before measurement.
Use this measurement for initial value.</td></tr>
<tr><td></td><td></td><td>Capacitance</td><td>Characteristics | Change from the value before test
X5R | ± 25 %</td></tr>
<tr><td></td><td></td><td>D. F.</td><td>characteristics
X5R : 200% of initial spec max.</td></tr>
<tr><td></td><td></td><td>Insulation Resistance</td><td>0.2 MΩ min.</td></tr>
</table>

(continued)

<table>
<tr><th>No.</th><th colspan="2">Item</th><th>Performance</th><th>Test or inspection method</th></tr>
<tr><td rowspan="4">15</td><td rowspan="4">Life</td><td>External appearance</td><td>No mechanical damage.</td><td rowspan="4">Reflow Solder the capacitors on a P. C. Board shown in Appendix2 before testing.

Apply rated voltage at 85±2℃ for 1, 000 +48, 0h.

Charge/discharge current shall not exceed 50mA.

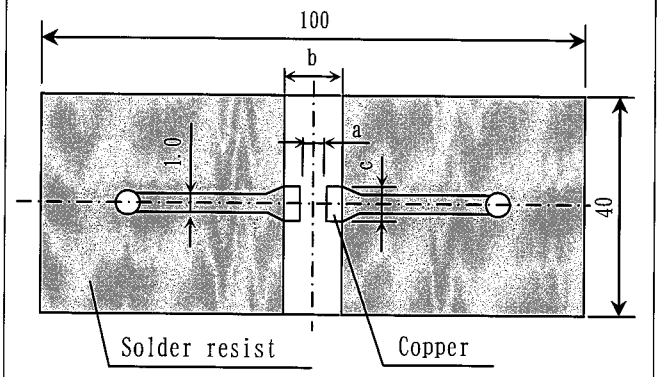
Leave the capacitors in ambient condition for 48±4h before measurement.

Voltage conditioning
Voltage treat the capacitor under testing temperature and voltage for 1hour.
Leave the capacitors in ambient condition for48±4h before measurement.
Use this measurement for initial value.</td></tr>
<tr><td>Capacitance</td><td><table><tr><th>Characteristics</th><th>Change from the value before test</th></tr><tr><td>X5R</td><td>± 25 %</td></tr></table></td></tr>
<tr><td>D. F.</td><td>characteristics
X5R: 200% of initial spec max.</td></tr>
<tr><td>Insulation Resistance</td><td>0. 4 MΩ min.</td></tr>
</table>

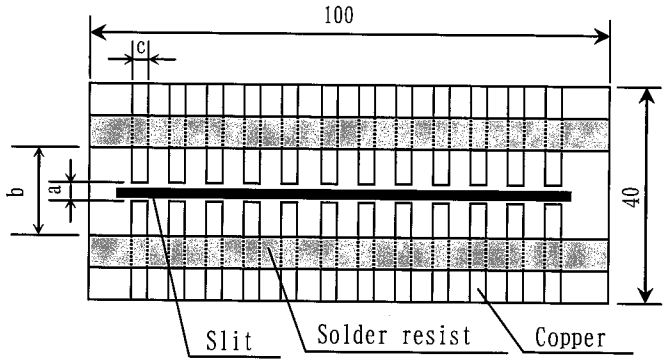
*As for the initial measurement of capacitors on number 6, 10, 11, 12 and 13, leave capacitors at 150 -10, 0℃ for 1h and measure the value after leaving capacitors for 48±4h in ambient condition.

Appendix1

P. C. Board for bending test



Appendix2



(Unit : mm)

Type	Dimensions		
TDK (EIA style)	a	b	c
C3225 (CC1210)	2.2	5.0	2.9

1. Material : Glass Epoxy (As per JIS C6484 GE4)

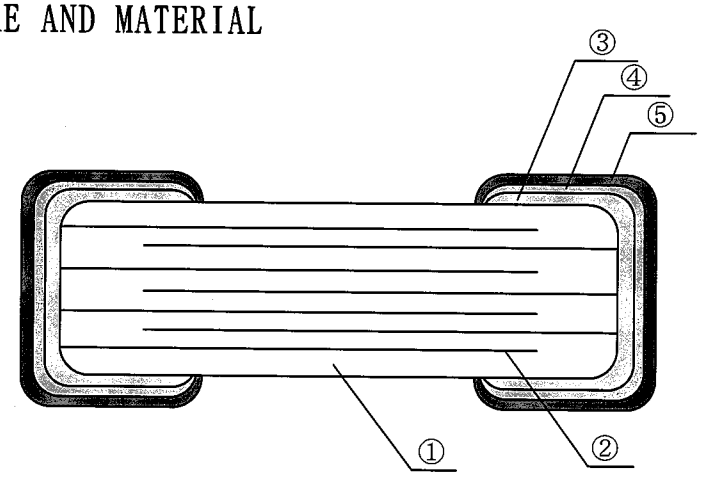
2. Thickness : 1.6mm

Copper (Thickness: 0.035mm)

Solder resist

TDK

INSIDE STRUCTURE AND MATERIAL



No.	NAME	MATERIAL
①	Dielectric	$BaTiO_3$
②	Electrode	Ni
③	Termination	Cu
④		Ni
⑤		Sn

PACKAGING

Packaging shall be done to protect the components from the damage during transportation and storing, and a label which has the following information shall be attached.

1) Total number of components in a plastic bag for bulk packaging : 1000pcs
2) Tape packaging is as per TDK tape packaging specification.

Information on label
1) Inspection No.
2) TDK P/N
3) Customer's P/N
4) Quantity

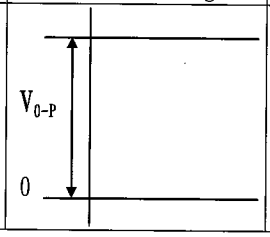
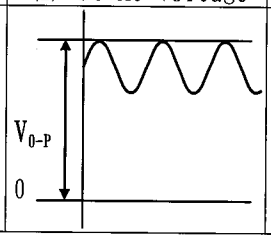
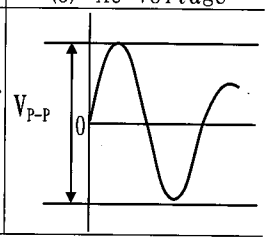
*Composition of Inspection No.

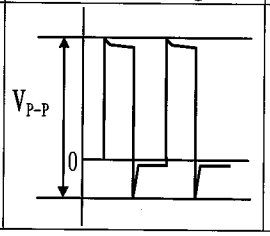
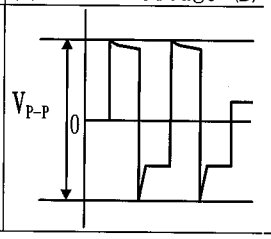
Example $\underset{(a)}{M}\ \underset{(b)}{1}\ \underset{(c)}{A} - \underset{(d)}{\bigcirc\bigcirc} - \underset{(e)}{\bigcirc\bigcirc\bigcirc}$

a) Line code
b) Last digit of the year
c) Month and A for January and B for February and so on. (Skip I)
d) Inspection Date of the month.
e) Serial No. of the day

Caution

No.	Process	Condition
1	Operating Condition (Storage, Transportation)	1-1. Storage 1) The capacitors must be stored in an ambient temperature of 5 to 40℃ with a relative humidity of 20 to 70%RH. The products should be used within 6 months upon receipt. 2) The capacitors must be operated and stored in an environment free of dew condensation and these gases such as Hydrogen Sulphide, Hydrogen Sulphate, Chlorine, Ammonia and sulfur. 3) Avoid storing in sun light and falling of dew. 4) Do not use capacitors under high humidity and high and low atmospheric pressure which may affect capacitors reliability. 5) Capacitors should be tested for the solderability when they are stored for long time. 1-2. Handling in transportation In case of the transportation of the capacitors, the performance of the capacitors may be deteriorated depending on the transportation condition. (Refer to JEITA RCR-2335B 9.2 Handling in transportation)
2	Circuit design ⚠ Caution	2-1. Operating temperature Operating temperature should be followed strictly within this specification, especially be careful with maximum temperature. 1) Do not use capacitors above the maximum allowable operating temperature. 2) Surface temperature including self heating should be below maximum operating temperature. (Due to dielectric loss, capacitors will heat itself when AC is applied. Especially at high frequencies around its SRF, the heat might be so extreme that it may damage itself or the product mounted on. Please design the circuit so that the maximum temperature of the capacitors including the self heating to be below the maximum allowable operating temperature. Temperature rise at capacitor surface shall be below 20℃) 3) The electrical characteristics of the capacitors will vary depending on the temperature. The capacitors should be selected and designed in taking the temperature into consideration. 2-2. Operating voltage 1) Operating voltage across the terminals should be below the rated voltage. When AC and DC are super imposed, V_{0-P} must be below the rated voltage. ——— (1) and (2) AC or pulse with overshooting, V_{P-P} must be below the rated voltage. ——— (3), (4) and (5) When the voltage is started to apply to the circuit or it is stopped applying, the irregular voltage may be generated for a transit period because of resonance or switching. Be sure to use the capacitors within rated voltage containing these Irregular voltage.

Voltage	(1) DC voltage	(2) DC+AC voltage	(3) AC voltage
Positional Measurement (Rated voltage)			

Voltage	(4) Pulse voltage (A)	(5) Pulse voltage (B)
Positional Measurement (Rated voltage)		

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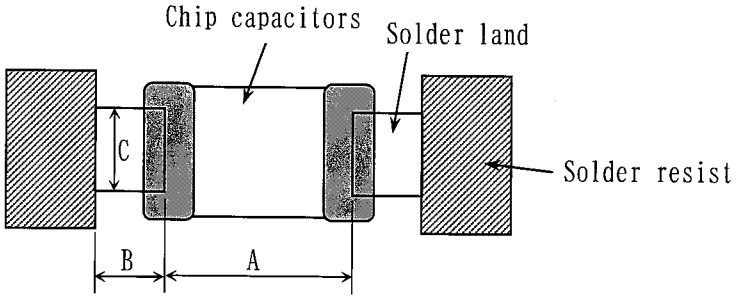
No.	Process	Condition
2	Circuit design ⚠ Caution	2) Even below the rated voltage, if repetitive high frequency AC or pulse is applied, the reliability of the capacitors may be reduced. 3) The effective capacitance will vary depending on applied DC and AC voltages. The capacitors should be selected and designed in taking the voltages into consideration. 2-3. Frequency When the capacitors (Class 2) are used in AC and/or pulse voltages, the capacitors may vibrate themselves and generate audible sound.
3	Designing P. C. board	The amount of solder at the terminations has a direct effect on the reliability of the capacitors. 1) The greater the amount of solder, the higher the stress on the chip capacitors, and the more likely that it will break. When designing a P. C. board, determine the shape and size of the solder lands to have proper amount of solder on the terminations. 2) Avoid using common solder land for multiple terminations and provide individual solder land for each terminations. 3) Size and recommended land dimensions.  Reflow soldering (mm) Type / Symbol: C3225 (CC1210) A: 2.0 ～ 2.4 B: 1.0 ～ 1.2 C: 1.9 ～ 2.5

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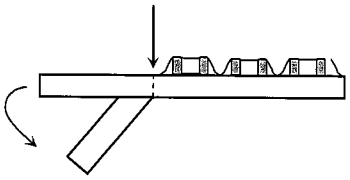
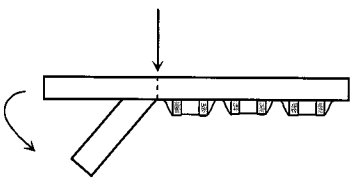
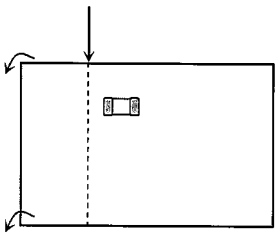
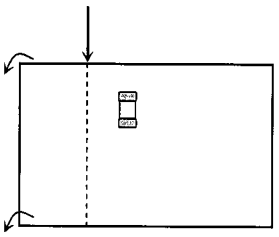
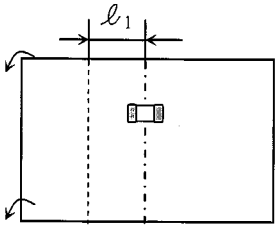
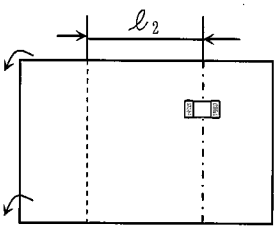
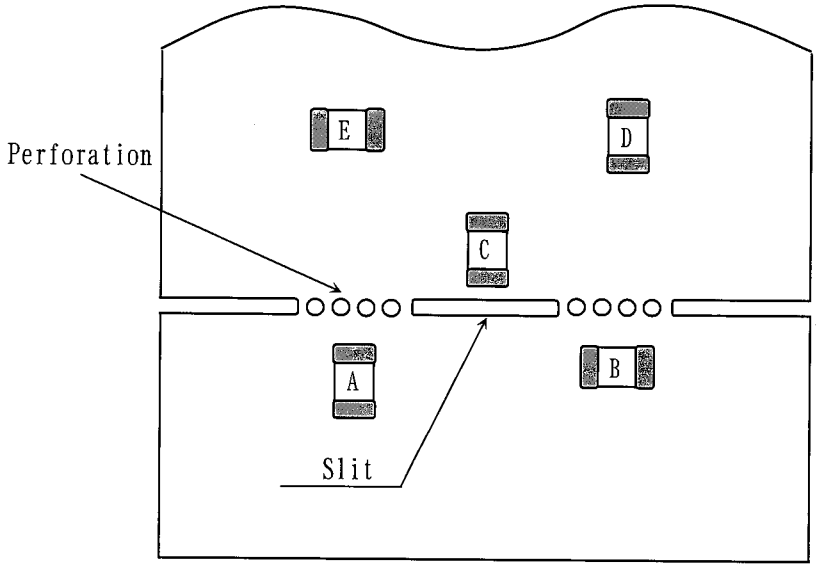
No.	Process	Condition
3	Designing P. C. board	4) Recommended chip capacitors layout is as following.

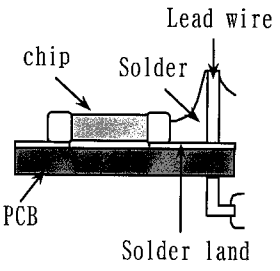
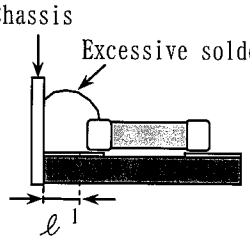
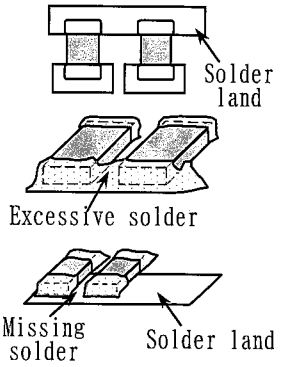
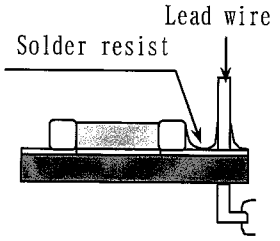
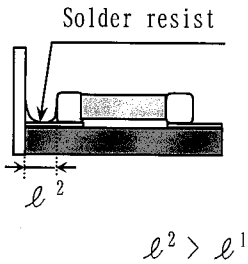
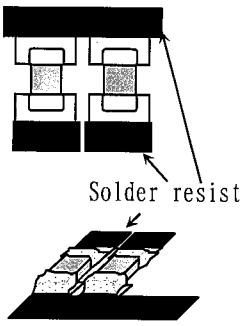
	Disadvantage against bending stress	Advantage against bending stress
Mounting face	Perforation or slit  Break P. C. board with mounted side up.	Perforation or slit  Break P. C. board with mounted side down.
Chip arrangement (Direction)	Mount perpendicularly to perforation or slit Perforation or slit 	Mount in parallel with perforation or slit Perforation or slit 
Distance from slit	Closer to slit is higher stress  $(\ell_1 < \ell_2)$	Away from slit is less stress  $(\ell_1 < \ell_2)$

No.	Process	Condition
3	Designing P. C. board	5) Mechanical stress varies according to location of chip capacitors on the P. C. board.



The stress in capacitors is in the following order.
A > B = C > D > E

6) Layout recommendation

Example	Use of common solder land	Soldering with chassis	Use of common solder land with other SMD
Need to avoid			
Recommen-dation			

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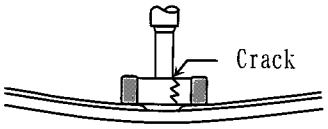
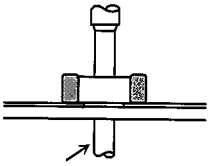
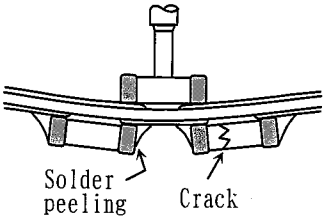
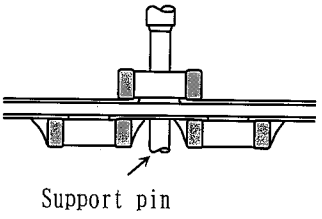
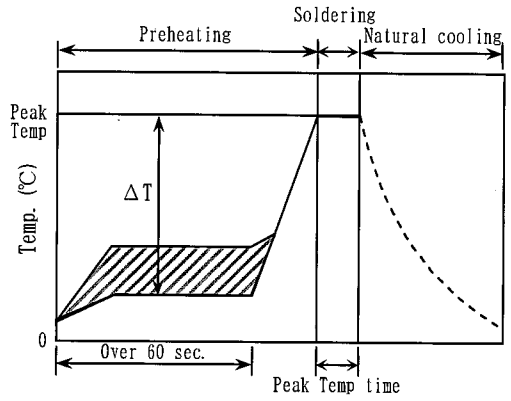
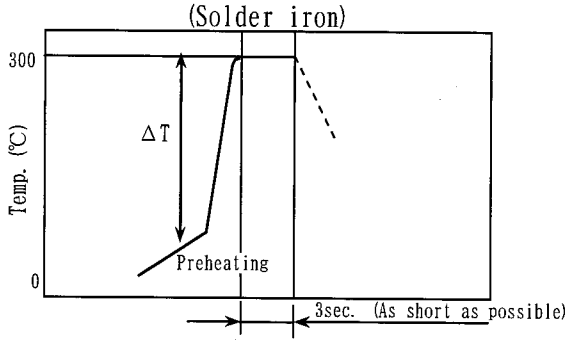
No.	Process	Condition
4	Mounting	4-1. Stress from mounting head If the mounting head is adjusted too low, it may induce excessive stress in the chip capacitors to result in cracking. Please take following precautions. 1) Adjust the bottom dead center of the mounting head to reach on the P. C. board surface and not press it. 2) Adjust the mounting head pressure to be 1 to 3N of static weight. 3) To minimize the impact energy from mounting head, it is important to provide support from the bottom side of the P. C. board. See following examples.

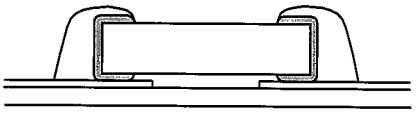
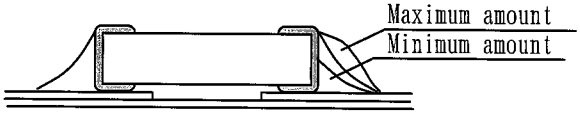
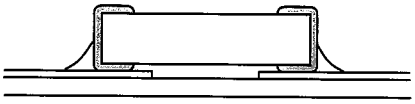
	Not recommended	Recommended
Single sided mounting		
Double-sides mounting		

When the centering jaw is worn out, it may give mechanical impact on the capacitors to cause crack. Please control the close up dimension of the centering jaw and provide sufficient preventive maintenance and replacement of it.

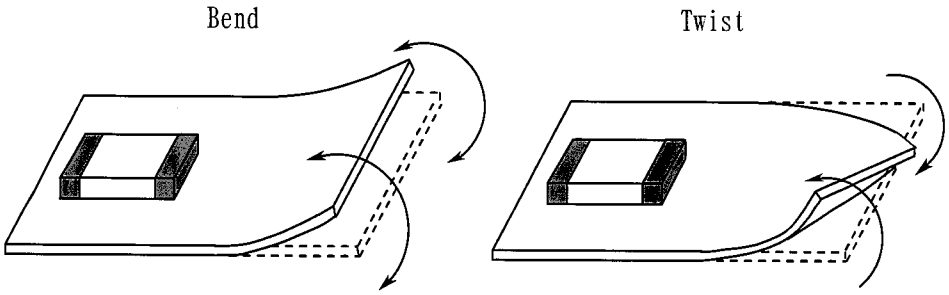
TDK

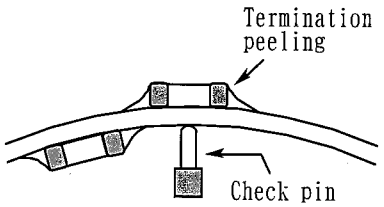
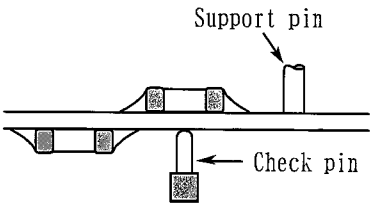
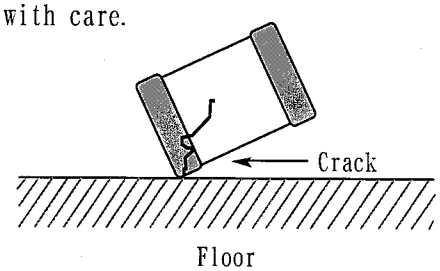
No.	Process	Condition
5	Soldering	5-1. Flux selection Although highly-activated flux gives better solderability, substances which increase activity may also degrade the insulation of the chip capacitors. To avoid such degradation, it is recommended following. 1) It is recommended to use a mildly activated rosin flux (less than 0.1wt% chlorine). Strong flux is not recommended. 2) Excessive flux must be avoided. Please provide proper amount of flux. 3) When water-soluble flux is used, enough washing is necessary. 5-2. Recommended soldering profile by various methods Reflow soldering  Manual soldering (Solder iron)  5-3. Recommended soldering peak temp and peak temp duration Temp./Duration / Solder: Reflow soldering Peak temp (℃) / Duration (sec.) Sn-Pb Solder: 230 max. / 20 max. Lead Free Solder: 260 max. / 10 max. Recommended solder compositions Sn-37Pb (Sn-Pb solder) Sn-3.0Ag-0.5Cu (Lead Free Solder)

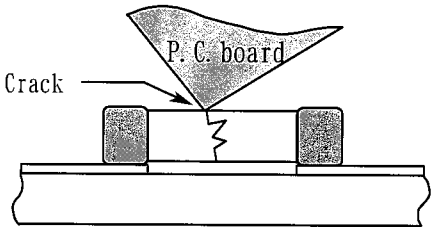
TDK

No.	Process	Condition
5	Soldering	5-4. Avoiding thermal shock 1) Preheating condition Soldering / Temp. (℃) Reflow soldering / ΔT ≦ 130 Manual soldering / ΔT ≦ 130 2) Cooling condition Natural cooling using air is recommended. If the chips are dipped into a solvent for cleaning, the temperature difference (ΔT) must be less than 100℃. 5-5. Amount of solder Excessive solder will induce higher tensile force in chip capacitors when temperature changes and it may result in chip cracking. In sufficient solder may detach the capacitors from the P. C. board. Excessive solder  Higher tensile force in chip capacitors to cause crack Adequate  Insufficient solder  Low robustness may cause contact failure or chip capacitors come off the P. C. board. 5-6. Solder repair by solder iron 1) Selection of the soldering iron tip Tip temperature of solder iron varies by its type, P. C. board material and solder land size. The higher the tip temperature, the quicker the operation. However, heat shock may cause a crack in the chip capacitors. Please make sure the tip temp. before soldering and keep the peak temp and time in accordance with following recommended condition. (Please preheat the chip capacitors with the condition in 5-4 to avoid the thermal shock.) Recommended solder iron condition (Sn-Pb Solder and Lead Free Solder) Temp. (℃) / Duration (sec.) / Wattage (W) / Shape (mm) 300 max. / 3 max. / 20 max. / φ3.0 max. 2) Direct contact of the soldering iron with ceramic dielectric of chip capacitors may cause crack. Do not touch the ceramic dielectric and the terminations by solder iron.

No.	Process	Condition
5	Soldering	5-7. Sn-Zn solder Sn-Zn solder affects product reliability. Please contact TDK in advance when utilize Sn-Zn solder. 5-8. Countermeasure for tombstone The misalignment between the mounted positions of the capacitors and the land patterns should be minimized. The tombstone phenomenon may occur especially the capacitors are mounted (in longitudinal direction) in the same direction of the reflow soldering. (Refer to JEITA RCR-2335B Annex A (Informative) Recommendations to prevent the tombstone phenomenon)
6	Cleaning	1) If an unsuitable cleaning fluid is used, flux residue or some foreign articles may stick to chip capacitors surface to deteriorate especially the insulation resistance. 2) If cleaning condition is not suitable, it may damage the chip capacitors. 2)-1. Insufficient washing (1) Terminal electrodes may corrode by Halogen in the flux. (2) Halogen in the flux may adhere on the surface of capacitors, and lower the insulation resistance. (3) Water soluble flux has higher tendency to have above mentioned problems (1) and (2). 2)-2. Excessive washing When ultrasonic cleaning is used, excessively high ultrasonic energy output can affect the connection between the ceramic chip capacitor's body and the terminal electrode. To avoid this, following is the recommended condition. Power : 20W/ℓ max. Frequency : 40kHz max. Washing time : 5 minutes max. 2)-3. If the cleaning fluid is contaminated, density of Halogen increases, and it may bring the same result as insufficient cleaning.
7	Coating and molding of the P. C. board	1) When the P. C. board is coated, please verify the quality influence on the product. 2) Please verify carefully that there is no harmful decomposing or reaction gas emission during curing which may damage the chip capacitors. 3) Please verify the curing temperature.

<table>
<tr><th>No.</th><th>Process</th><th>Condition</th></tr>
<tr><td>8</td><td>Handling after chip mounted
⚠ Caution</td><td>1) Please pay attention not to bend or distort the P. C. board after soldering in handling otherwise the chip capacitors may crack.
 

2) When functional check of the P. C. board is performed, check pin pressure tends to be adjusted higher for fear of loose contact. But if the pressure is excessive and bend the P. C. board, it may crack the chip capacitors or peel the terminations off. Please adjust the check pins not to bend the P. C. board.
<table>
<tr><th>Item</th><th>Not recommended</th><th>Recommended</th></tr>
<tr><td>Board bending</td><td> 
</td><td> 
</td></tr>
</table></td></tr>
<tr><td>9</td><td>Handling of loose chip capacitors</td><td>1) If dropped the chip capacitors may crack. Once dropped do not use it. Especially,
the large case sized chip capacitors are tendency to have cracks easily, so please handle with care.
 

2) Piling the P. C. board after mounting for storage or handling, the corner of the P. C. board may hit the chip capacitors of another board to cause crack.
 
</td></tr>
</table>

TDK

No.	Process	Condition
10	Capacitance aging	The capacitors (Class 2) have aging in the capacitance. They may not be used in precision time constant circuit. In case of the time constant circuit, the evaluation should be done well.
11	Estimated life and estimated failure rate of capacitors	As per the estimated life and the estimated failure rate depend on the temperature and the voltage. This can be calculated by the equation described in JEITA RCR-2335B Annex 6 (Informative) Calculation of the estimated lifetime and the estimated failure rate (Voltage acceleration coefficient : 3 multiplication rule, Temperature acceleration coefficient : 10℃ rule) The failure rate can be decreased by reducing the temperature and the voltage but they will not be guaranteed.
12	Others ⚠ Caution	The products listed on this specification sheet are intended for use in general electronic equipment (AV equipment, telecommunications equipment, home appliances, amusement equipment, computer equipment, personal equipment, office equipment, measurement equipment, industrial robots) under a normal operation and use condition. The products are not designed or warranted to meet the requirements of the applications listed below, whose performance and/or quality require a more stringent level of safety or reliability, or whose failure, malfunction or trouble could cause serious damage to society, person or property. Please understand that we are not responsible for any damage or liability caused by use of the products in any of the applications below or for any other use exceeding the range or conditions set forth in this specification sheet. If you intend to use the products in the applications listed below or if you have special requirements exceeding the range or conditions set forth in this specification, please contact us. (1) Aerospace/Aviation equipment (2) Transportation equipment (cars, electric trains, ships, etc.) (3) Medical equipment (4) Power-generation control equipment (5) Atomic energy-related equipment (6) Seabed equipment (7) Transportation control equipment (8) Public information-processing equipment (9) Military equipment (10) Electric heating apparatus, burning equipment (11) Disaster prevention/crime prevention equipment (12) Safety equipment (13) Other applications that are not considered general-purpose applications When designing your equipment even for general-purpose applications, you are kindly requested to take into consideration securing protection circuit/device or providing backup circuits in your equipment.

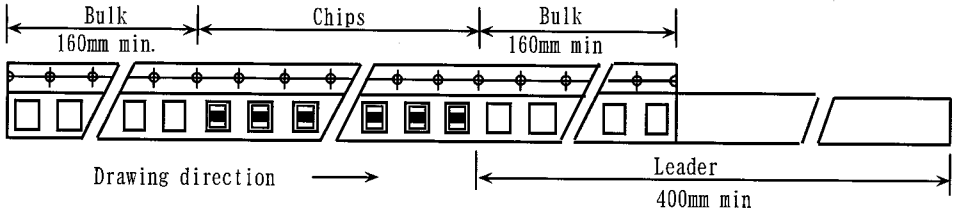
TAPE PACKAGING SPECIFICATION

TDK

1. CONSTRUCTION AND DIMENSION OF TAPING

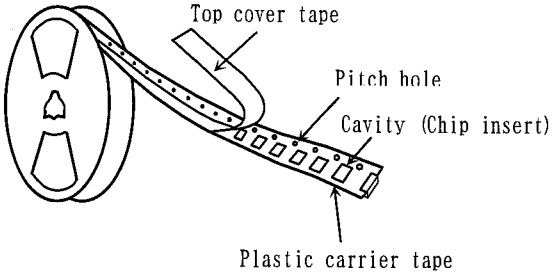
1-1. Dimensions of carrier tape
Dimensions of plastic tape shall be according to Appendix 3.

1-2. Bulk part and leader of taping



1-3. Dimensions of reel
Dimensions of ϕ178 reel shall be according to Appendix 4.
Dimensions of ϕ330 reel shall be according to Appendix 5.

1-4. Structure of taping

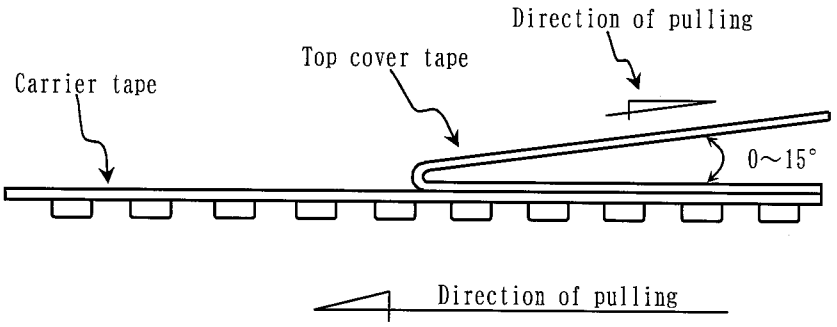


2. CHIP QUANTITY

Type	Thickness of chip	Taping Material	Chip quantity (pcs.)	
			ϕ178mm reel	ϕ330mm reel
C3225	2.50 mm	plastic	1,000	5,000

3. PERFORMANCE SPECIFICATIONS

3-1. Fixing peeling strength (top tape)
0.05-0.7N. (See the following figure.)



3-2. Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.

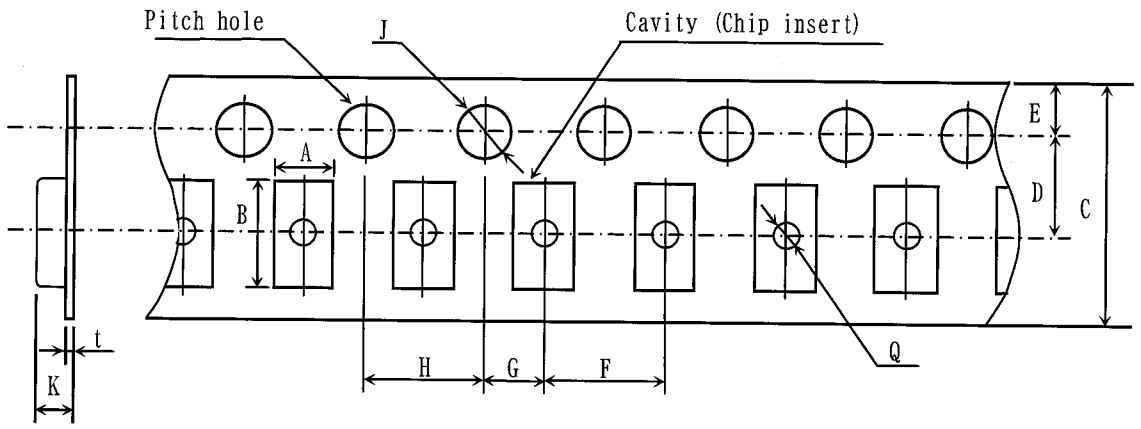
3-3. The missing of components shall be less than 0.1%

3-4. Components shall not stick to fixing tape.

3-5. The fixing tapes shall not protrude beyond the edges of the carrier tape nor shall cover the sprocket holes.

Appendix 3

Plastic Tape



(Unit : mm)

Symbol / Type	A	B	C	D	E	F
C3225	* (2.9)	* (3.6)	12.0±0.3	5.5±0.05	1.75±0.1	4.0±0.1

Symbol / Type	G	H	J	K	t	Q
C3225	2.0±0.05	4.0±0.1	$\phi 1.5^{+0.1}_{0}$	3.2 max.	0.6 max.	ϕ0.5 min.

* Referenced value

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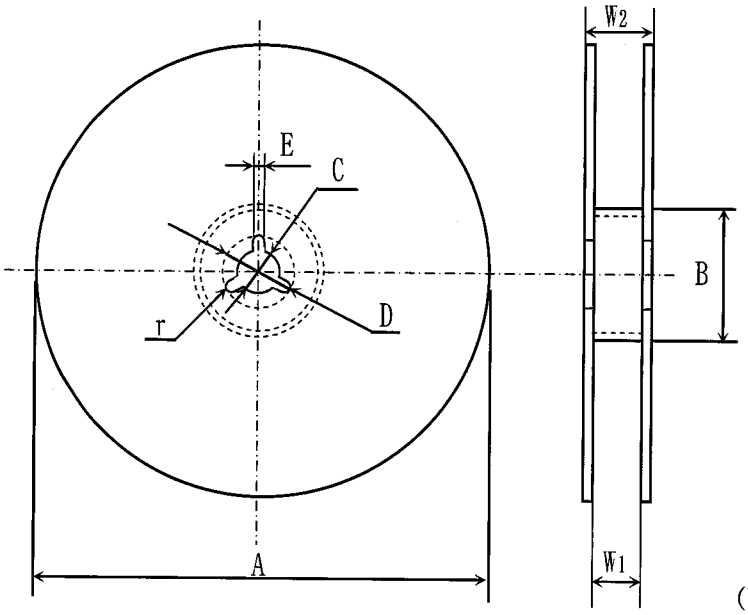
Appendix 4 (Reel material : Polystyrene)

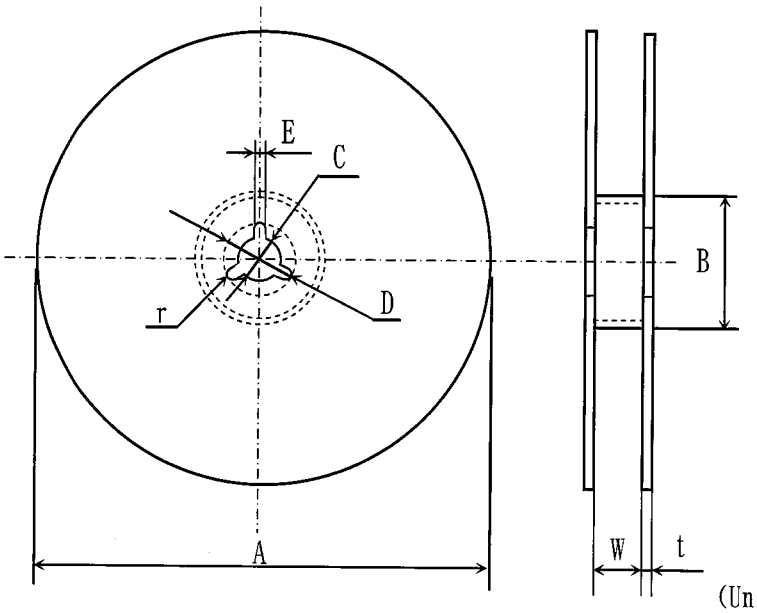


(Unit : mm)

Symbol	A	B	C	D	E	W1
Dimension	φ178±2.0	φ60±2.0	φ13±0.5	φ21±0.8	2.0±0.5	13.0±0.3

Symbol	W2	r
Dimension	17.0±1.4	1.0

Appendix 5 (Reel material : Polystyrene)



(Unit : mm)

Symbol	A	B	C	D	E	W
Dimension	φ382 max. (Nominal φ330)	φ50 min.	φ13±0.5	φ21±0.8	2.0±0.5	14.0±1.5

Symbol	t	r
Dimension	2.0±0.5	1.0

TDK